

November 25, 2003

NEWS AND ANNOUNCEMENTS

Teradyne Introduces New Software Programming Environment for XStation™ AXI Systems

Teradyne's Assembly Test Division announced and demonstrated the new XFrame™ program development environment at Productronica, the Munich trade fair held November 11-14. The PC-based software significantly reduces programming time and improves the consistency and quality of inspection programs for Teradyne's XStation family of AXI systems. By cutting programming time to hours, XFrame contributes to the XStation's status as the only "production-ready" AXI system.

http://www.teradyne.com/prods/cbt/news/newsdesk/82news_pr_11112003.html

UPCOMING EVENTS

TEST FORUM 2003, Denmark, December 2-3, 2003

Teradyne's Michael J. Smith, Assembly Test Division, will participate in a panel discussion on the impact of AOI & AXI on in-circuit and functional test at the Test Forum 2003 in Denmark. He will also make a presentation on the business and technology issues that drive imaging inspection. This event is sponsored by the Nordic Test Forum (NTF), an industry organization for people involved in the production test of electronics.

http://www.teradyne.com/prods/cbt/news/tradeshows/nordic_2003.html

TERADYNE WEBINAR SERIES "Are You Ready for 2004?", December 10, 2003

Join us for the first in a series of three Web-based seminars designed to prepare you for the test and inspection challenges coming next year. The first Webinar on December 10 will cover the business issues and technology drivers that are shaping PCB test and inspection. Webinar number two will focus on the impact of lead-free solder on test and inspection. The final Webinar will explain the impact of low-voltage devices on in-circuit test. Attend this three-part Webinar series to find out what test & inspection issues you will be facing in 2004 and how to deal with them. To register for the December 10 Webinar, go to:

http://www.teradyne.com/prods/cbt/news/tradeshows/2003_webinarseries.html

TERADYNE USER GROUP (TUG), San Jose, CA, May 3-4, 2004 Call for Papers

It's time to think about presenting a paper at TUG 2004. The deadline for paper abstracts is November 21. The conference theme is "Do More in '04." Assembly Test: Mil/Aero Test Solutions sessions are for users whose interests encompass areas traditionally referred to as FBT (Functional Board Test). Test engineers involved in developing, architecting, or maintaining factory, depot, or intermediate (I-Level) functional board or box test program sets will want to attend. This includes users of the Spectrum™ 91xx or L-Series Functional Test Systems, as well as users of the M9-Series™ Digital Test Instrument, the Ai7™ Analog Test Instrument, the Bi4-Series™ Serial Bus Test Instrument, TestStudio™, LASAR™, and VICTORY™. To submit a paper abstract online, go to:

<http://www.teradyne.com/prods/tug/t04cfp.html>

RECENT TECHNICAL PAPERS, ARTICLES, & PUBLICATIONS

XFrame™ Software Data Sheet

Find out more about the new XFrame program development software for XStation AXI systems. This data sheet explains the unique features of XFrame that let you develop an initial inspection program and have it ready for debug in under an hour.

<http://www.teradyne.com/prods/cbt/products/library/xray/xFrameDS160.pdf>

XStation HS™ Technology Backgrounder

Confused about AXI technology? Wondering if AXI has a place on your production line, and if so, what to look for in an AXI machine? Check out this technology backgrounder and find out the top 10 reasons why the Teradyne XStation should be your choice.

http://www.teradyne.com/prods/cbt/products/library/xray/XStationHS_10reasons.pdf

Technology Leader Series: Test & Measurement World, November 2003

This month's issue of Test & Measurement World magazine features Teradyne's SafeTest™ technology for safe testing of low-voltage devices at in-circuit test. In "Keep pc-board testing from harming low-voltage devices," T&MW editors tackle the topic in all its technical detail. Read about it at the T&MW Web site:

http://www.teradyne.com/prods/cbt/products/library/teststation/keep_nov2003.pdf

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